

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ALEKSANDAR ALEKSOV	06/22/2017
TELESPHOR KAMGAING	06/22/2017
SRI RANGA SAI BOYAPATI	07/06/2017
KRISTOF DARMAWIKARTA	06/22/2017
EYAL FAYNEH	06/29/2017
OFIR DEGANI	06/28/2017
DAVID LEVY	06/27/2017
JOHANNA M. SWAN	06/22/2017
RECEIVING PARTY DATA	
Name:	Intel Corporation
Street Address:	2200 Mission College Boulevard
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16604144
CORRESPONDENCE DATA	
Fax Number:	(503)796-2900
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(503) 222-9981
Email:	lpuccinelli@schwabe.com
Correspondent Name:	JUSTIN K. BRASK
Address Line 1:	1211 SW 5TH AVENUE, STE. 1600
Address Line 4:	PORTLAND, OREGON 97204
ATTORNEY DOCKET NUMBER:	P115821PCT-US
NAME OF SUBMITTER:	JUSTIN K. BRASK
SIGNATURE:	/Justin K. Brask/

DATE SIGNED:	11/01/2021
Total Attachments: 10 source=P115821PCT ASSIGN Executed#page1.tif source=P115821PCT ASSIGN Executed#page2.tif source=P115821PCT ASSIGN Executed#page3.tif source=P115821PCT ASSIGN Executed#page4.tif source=P115821PCT ASSIGN Executed#page5.tif source=P115821PCT ASSIGN Executed#page6.tif source=P115821PCT ASSIGN Executed#page7.tif source=P115821PCT ASSIGN Executed#page8.tif source=P115821PCT ASSIGN Executed#page9.tif source=P115821PCT ASSIGN Executed#page10.tif	

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Aleksandar Aleksov, Telesphor Kamgaing, Sri Ranga Sai Boyapati, Kristof Darmawikarta, Eyal Fayneh, Ofir Degani, David Levy, Johanna M. Swan

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

In-Package RF Waveguides As High Bandwidth Chip-To-Chip Interconnects And Methods For Using The Same

(I hereby authorize and request my attorney, associated with customer number 45209, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on June 19, 2017 as

United States Application Number PCT/US17/38114 and
COUNTRY or International Office

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below.

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and

the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

 Aleksandar Aleksov	<u>6/22/2017</u> Date signed
 Telesphor Kamgaing	<u>6/22/2017</u> Date signed
 Sri Ranga Sai Boyapati	 Date signed
 Kristof Darmawikarta	<u>6/22/2017</u> Date signed
 Eyal Fayneh	 Date signed
 Ofir Degani	 Date signed
 David Levy	 Date signed
 Johanna M. Swan	<u>6/22/2017</u> Date signed

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Date signed

Telesphor Kamgaing

Date signed



Sri Ranga Sai Boyapati

7/6/17

Date signed

Kristof Darmawikarta

Date signed

Eyal Payneh

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Attorney Docket No.: 42P115821PCT

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Telesphor Kamgaing	Date signed
Sri Ranga Sai Boyapati	Date signed
Kristof Darmawikarta	Date signed
<i>Eyal Fayneh</i> Eyal Fayneh	<i>23/06/2017</i> Date signed
Ofir Degani	Date signed
David Levy	Date signed
Johanna M. Swan	Date signed

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Sri Ranga Sai Boyapati

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Eyal Fayneh

Date signed



Ofir Degani

28/06/2017

Date signed

David Levy

Date signed

Johanna M. Swan

Date signed

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<hr/> <i>David Levy</i>	<hr/> 6/27/2017
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